



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

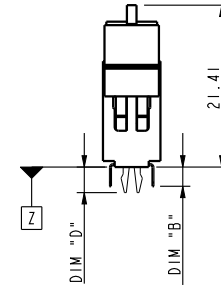
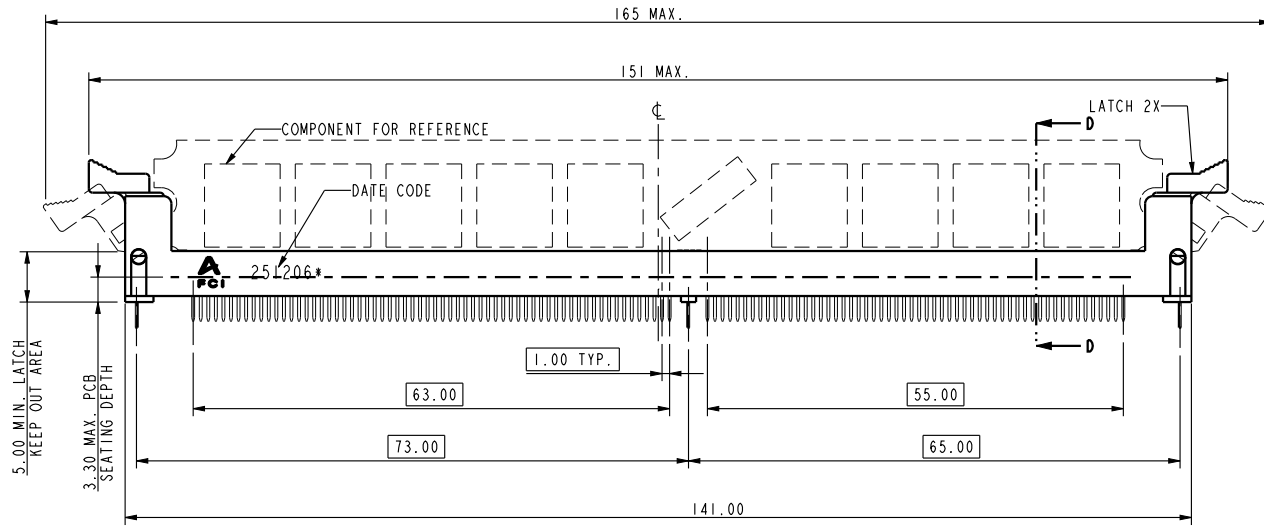
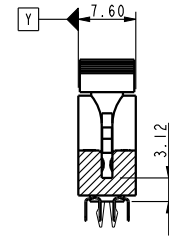
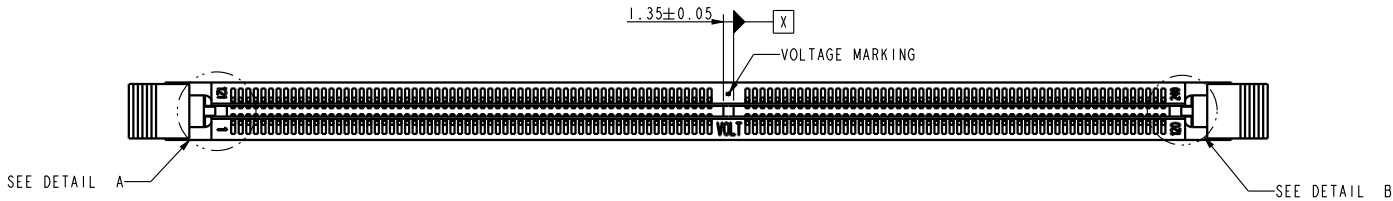
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

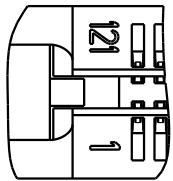


Amphenol
FCi

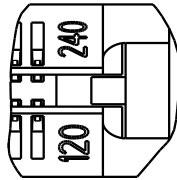
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tolerances unless otherwise specified		
linear	.X	±0.38
	.XX	±0.25
	.XXX	±0.13
angles	X°	±2°

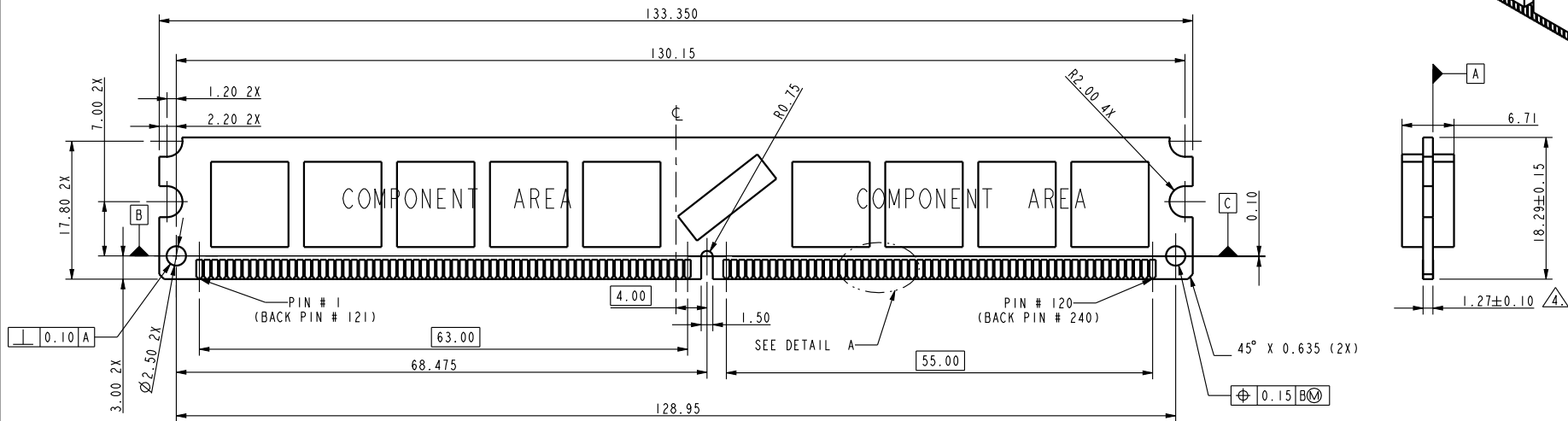
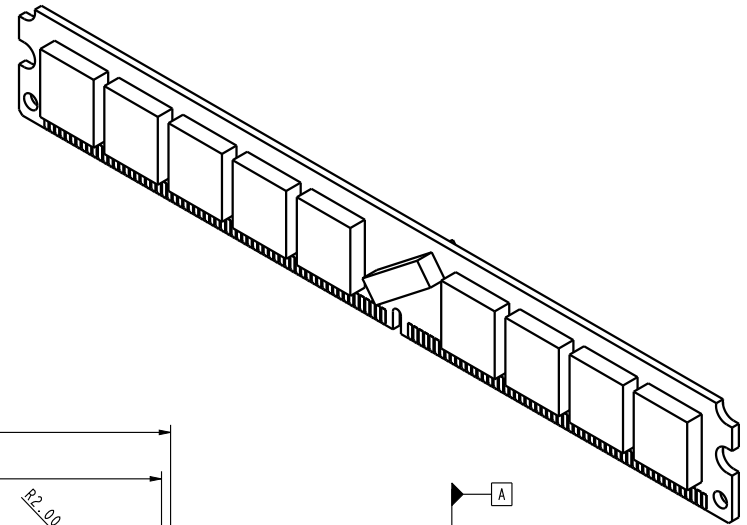


DETAIL A
SCALE 3.000

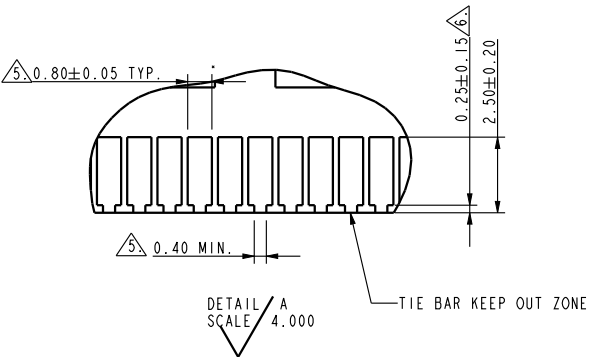


DETAIL B
SCALE 3.000

dr	Rick Bian	2010/07/08	projection 	MM ←→	size	A4	scale	1.000	
eng	Jeny Ren	2018/01/26			ecn no	ELX-DG-28708-1			
chr	-	-			rel level	Released			
appr	Nickor Zuo	2018/01/29	product family		rev	F			
Amphenol FCI		title			DDR II VERY LOW PROFILE		dwg no		10052286
					SOCKET ASSEMBLY				
cat. no.		*			Product - Customer Drw		sheet 1 of 4		



RECOMMENDED MODULE LAYOUT (PER JEDEC MO-XXX)



tolerances unless otherwise specified		
linear	.X	±0.38
	.XX	±0.25
	.XXX	±0.13
angles	X°	±2°

dr	Rick Bian	2010/07/08	projection 	MM ←→	size	A4	scale	1.000
eng	Jeny Ren	2018/01/26			ecn no	ELX-DG-28708-1		
chr	-	-			rel level	Released		
appr	Nickor Zuo	2018/01/29	product family		rev			
Amphenol FCi		title			10052286		F	
		DDRII VERY LOW PROFILE SOCKET ASSEMBLY			dwg no		sheet 2 of 4	
cat. no.		Product - Customer Drw			sheet 2 of 4			

A

B

C

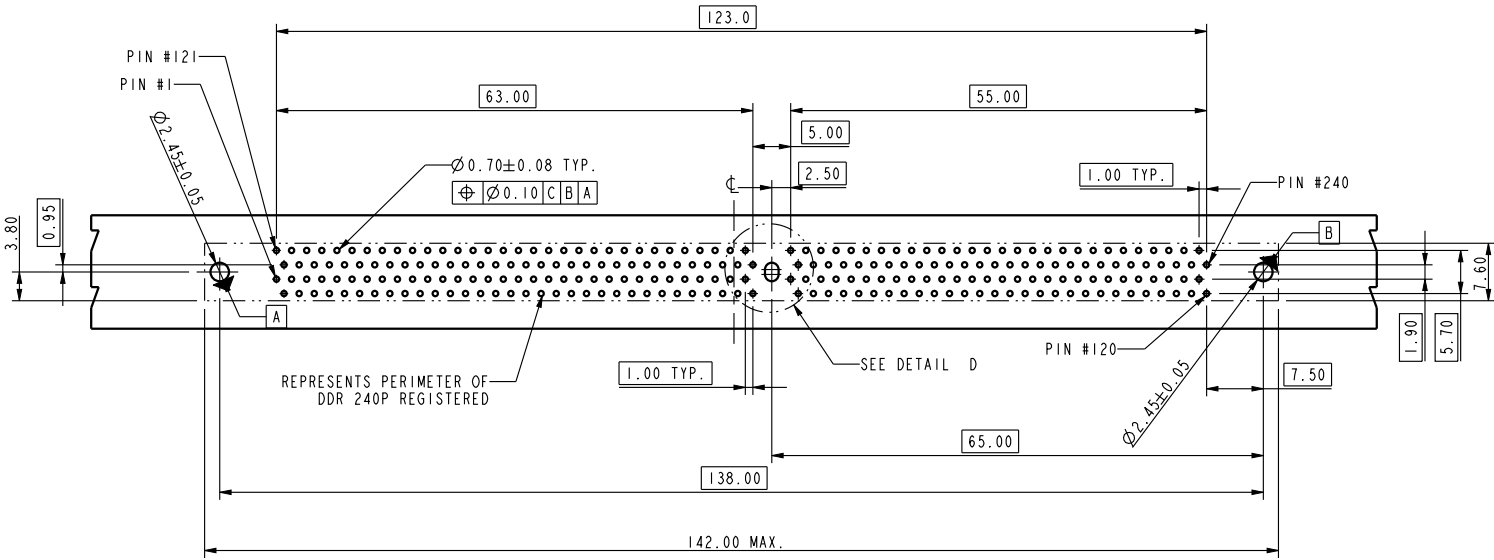
D

A

B

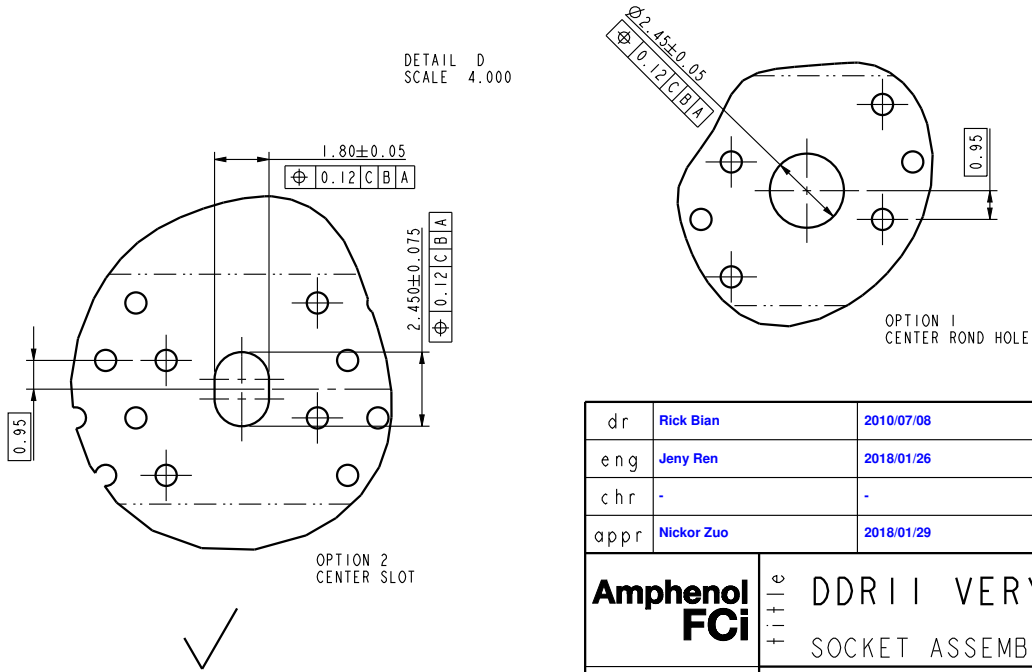
C

D



RECOMMENDED CIRCUIT BOARD HOLE LAYOUT

DETAIL D
SCALE 4.000



tolerances unless otherwise specified		
linear	.X	±0.38
	.XX	±0.25
	.XXX	±0.13
angles	X°	±2°

dr	Rick Bian	2010/07/08	projection 	MM 	size	A4	scale	0.500			
eng	Jeny Ren	2018/01/26			ecn no	ELX-DG-28708-1					
chr	-	-			rel level	Released					
appr	Nickor Zuo	2018/01/29	product family								
Amphenol FCi		title			DDR II VERY LOW PROFILE		dwg no		10052286	rev	F
		cat. no.			Product - Customer Drw		sheet 3 of 4				

10052286 -

STYLE : MECHANICAL KEYING

- 1 : 1.8 VOLT. W/TYPE "C"
- 2 : 2.5 VOLT. W/TYPE "L"
- 3 : X.X VOLT. W/TYPE "R"

METAL CLIP

- 1 : WITH METAL CLIP + DIM."D"=3.05
- 2 : WITH METAL CLIP + DIM."D"=3.56
- 3 : WITH METAL CLIP + DIM."D"=3.43

TAIL LENGTH

CODE	DIM. "B"	PCB THICKNESS
0	2.54	1.47 mm (0.058")
1	2.67	1.60 mm (0.063")
2	3.18	2.36 mm (0.093")
3	4.00	3.18 mm (0.125")

PLATING

CODE	CONTACT	SOLDERTAIL	UNDERPLATE
2	15u" (0.38um) MIN. GOLD	100u" (2.54um) MIN. TIN/LEAD	50u" (1.27um) MIN. NICKEL OVERALL
3	30u" (0.76um) MIN. GOLD		
4	3u" (0.076um) MIN. GOLD		
7LF	15u" (0.38um) MIN. GOLD	100u" (2.54um) MIN. 100% TIN	50u" (1.27um) MIN. NICKEL OVERALL
8LF	30u" (0.76um) MIN. GOLD		
9LF	3u" (0.076um) MIN. GOLD		

COLOR OF HOUSING AND EJECTOR

- 0 : BLACK HOUSING + IVORY EJECTOR
- 1 : BLUE HOUSING + IVORY EJECTOR
- 2 : BLACK HOUSING + BLACK EJECTOR

NOTES:

1. MATERIAL:
HOUSING: HIGH PERFORMANCE RESINS, GLASS FILLED UL94V-0 RATED.
EJECTOR: HIGH PERFORMANCE RESINS, GLASS FILLED UL94V-0 RATED.
TERMINAL: PHOSPHOR BRONZE.
METAL CLIP: COPPER ALLOY.
2. FCI LOGO TO BE APPROXIMATELY LOCATED AS SHOWN ON PRINT.
3. PRODUCT SPECIFICATION: GS-12-352.
- ⚠️ CARD THICKNESS APPLIES ACROSS TABS AND INCLUDES PLATING AND/OR METALIZATION.
- ⚠️ LEADING EDGE OF CONTACT PADS SPECIFIED BY THE KEEP OUT ZONE SHALL BE FREE OF BURRS AND EXTERNAL TIE BARS. FOR OPTIMUM PERFORMANCE. THE TIE BAR IS TO BE ON AN INTERNAL LAYER SO THAT THE REMNANT CANNOT CAUSE CONTACT DAMAGE.
6. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
7. THE HOUSING WILL WITH STAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION.
8. DATE CODE:XXXXXX* MEANS MONTH/DAY/YEAR.
"*" MEANS PRODUCTION LINE CODE.



dr	Rick Bian	2010/07/08	projection 	MM 	size	A4	scale	0.500	
eng	Jeny Ren	2018/01/26			ecn no	ELX-DG-28708-1			
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appr	Nickor Zuo	2018/01/29	product family		rev	F			
Amphenol FCI		title			DDR II VERY LOW PROFILE		dwg no		10052286
					SOCKET ASSEMBLY				
cat. no.		*			Product - Customer Drw		sheet 4 of 4		